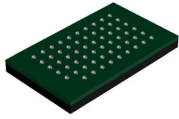
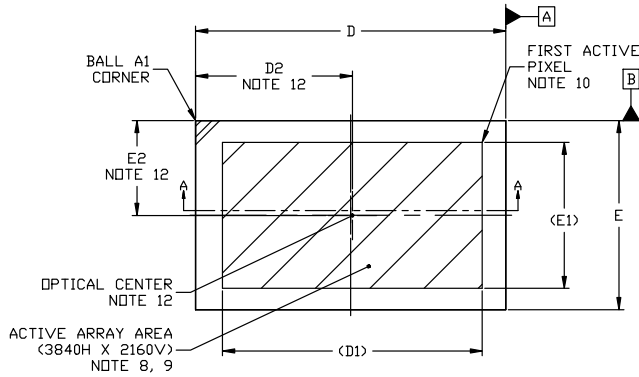


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

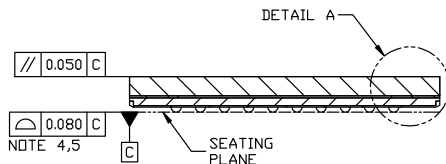


**ODCSP59 6.41x3.91x0.63, 0.50P**  
CASE 570AY  
ISSUE O

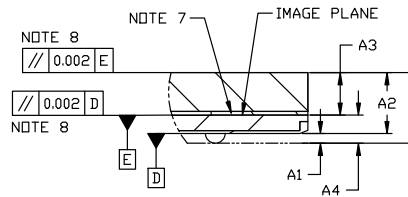
DATE 15 NOV 2023



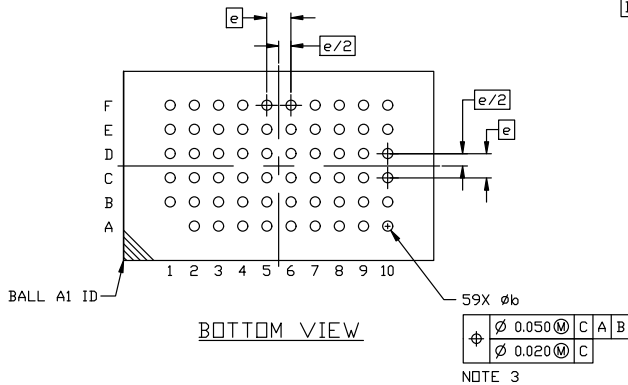
TOP VIEW



SECTION A-A

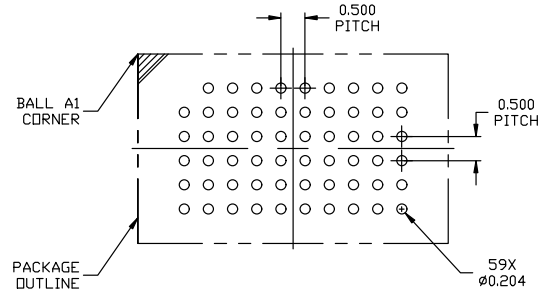


DETAIL "A"  
SCALE 2:1



BOTTOM VIEW

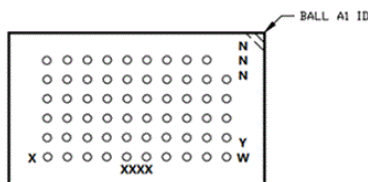
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	0.762
A1	0.081	0.101	0.121
A2	0.631 REF.		
A3	0.425	0.440	0.455
A4	0.252	0.292	0.332
b	0.184	0.204	0.224
D	6.392	6.417	6.442
D1	5.376 REF.		
D2	3.218	3.243	3.268
E	3.889	3.914	3.939
E1	3.024 REF.		
E2	1.937	1.962	1.987
e	0.500 BSC		



RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

## GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
Y = Year  
W = Work Week  
NNN = Serial Number

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>ODCSP59 6.41x3.91x0.63, 0.50P</b>	<b>PAGE 1 OF 1</b>

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